

ABSTRACT

An epoxy resin composition suitable for encapsulating electronic parts such as diodes, transistors, integrated circuits and the like comprising:

- (A) an epoxy resin;
- (B) a phenolic novolac curing agent
- (C) an inorganic silica filler of mixed crystalline and fused types with:
 - (i) total filler content at 70-90% by weight based on the total resin composition; and
 - (ii) ratio of crystalline/fused: 0.3-1.5; and
- (D) a curing accelerator.

Suitably, the weight percentages of the components of the total resin composition fall within the following ranges:

- (A) 6% to 20%
- (B) 3% to 12%
- (C) 70% to 90%
- (D) 0.05% to 0.8%

and the ratio of (A) to (B) is between 1.2 to 2.5.



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